



Henkel Solutions for Laminate Packaging Printable BOC Die Attach Materials

PRODUCT	DESCRIPTION	KEY ATTRIBUTES	VISCOSITY, BROOKFIELD CP51 AT 25°C AND 5 RPM (CP)	GLASS TRANSITION TEMPERATURE, TG, BY TMA (°C)	CTE (ppm/°C)		RECOMMENDED B-STAGE CONDITION	CURE SCHEDULE
					Below T _g	Above T _g		
LOCTITE ABLESTIK 6200	B-stageable die attach adhesive	<ul style="list-style-type: none"> • Stencil printing • Low moisture uptake • Low bleed • Ideal for chip scale packages where tolerance and bleed need to be minimized • Oven cure • Designed for flex or laminate based substrates 	21,000	-10	94	237	60 min. at 120°C	30 min. ramp + 60 min. soak at 175°C
LOCTITE ABLESTIK 6202C	B-stageable die attach adhesive	<ul style="list-style-type: none"> • Stencil printing • Low warpage • Ideal for chip scale packages where tolerance and bleed need to be minimized • Oven cure • Recommended for large die sizes • Designed for laminate based substrates 	28,000	40	70	350	1 hr. at 125°C	30 min. ramp + 60 min. soak at 175°C
LOCTITE ABLESTIK 6202C-X	B-stageable die attach adhesive	<ul style="list-style-type: none"> • Small particle size • Stencil printing • Low warpage • Ideal for chip scale packages where tolerance and bleed need to be minimized • Oven cure • Recommended for large die sizes • Designed for laminate based substrates 	30,000	40	70	232	30 min. ramp + 90 min. soak at 125°C + 30 min. ramp down to 25°C in vented magazine in oven with good air flow	30 min. ramp + 90 min. soak at 90°C + 30 min. ramp and 60 min. soak at 175°C in vented magazine in oven with good air flow

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